Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	5 X 5 X 1.45
Lead Count	32
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes with exemption
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	5.53E-02	93.7	937000	51.95	519516
Thermosets	Epoxy resin	Proprietary	1.77E-03	3.0	30000	1.66	16633
Thermosets	Phenol resin	Proprietary	1.77E-03	3.0	30000	1.66	16633
Other inorganic materials	Carbon black	1333-86-4	1.77E-04	0.3	3000	0.17	1663
Subtotal			5.90E-02	100.00	1000000	55.44	554446

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.84 E-02	96.20	962000	26.69	266914
Copper & its alloys	Nickel	7440-02-0	8.86 E-04	3.00	30000	0.83	8324
Copper & its alloys	Silicon	7440-21-3	1.92 E-04	0.65	6500	0.18	1803
Copper & its alloys	Magnesium	7439-95-4	4.43 E-05	0.15	1500	0.04	416
Subtotal			2.95 E-02	100.00	1000000	27.75	277458

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.50 E-04	100.0	1000000	0.33	3290

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	2.50 E-04	100.0	1000000	0.23	2350

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	8.32 E-04	99.0	990000	0.78	7816
Precious metals	Palladium	7440-05-3	8.40 E-06	1.00	10000	0.008	79
Subtotal			8.40 E-04	100.0	1000000	0.79	7895

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	8.40 E-03	100.0	1000000	7.90	78951

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other organic materials	Resin	Proprietary	3.58 E-03	50	500000	3.36	33648
Other organic materials	Ethene, tetrafluoro-,homopolymer	9002-84-0	3.22 E-03	45	450000	3.03	30284
Other organic materials	[3-(2,3-Epoxypropoxy)propyl]trimethoxysilane	2530-83-8	3.58 E-04	5	50000	0.34	3365
Subtotal			7.16 E-03	100.0	1000000	6.73	67297

Seal Glass

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Ceramics/Glass	Lead borosilicate glass	65997-17-3	7.74 E-04	87.5	875000	0.73	7274
Ceramics/Glass	Aluminosilicate glass	65997-17-3	1.11 E-04	12.5	125000	0.10	1039
			8.85 E-04			0.83	8314

	Weight (g)	Percentage (%)	PPM
Package Totals	**1.06 E-01**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary